MOSFETs Silicon N-channel MOS (U-MOSIX-H)

XPH1R104PS

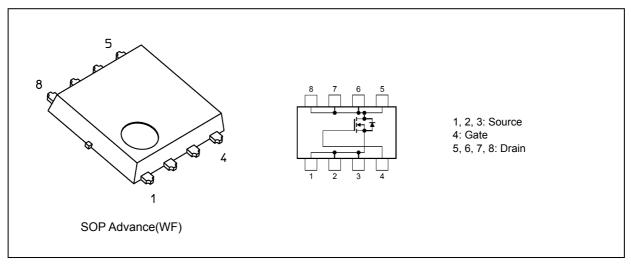
1. Applications

- Automotive
- Motor Drivers
- Switching Voltage Regulators

2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Low drain-source on-resistance: $R_{\rm DS(ON)}$ = 0.95 mO (typ.) (V_{\rm GS} = 10 V)
- (4) Low leakage current: I_{DSS} = 10 μ A (max) (V_{DS} = 40 V)
- (5) Enhancement mode: V_{th} = 2.0 to 3.0 V (V_{DS} = 10 V, I_D = 0.5 mA)

3. Packaging and Internal Circuit



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4. Absolute Maximum Ratings (Note) ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

Characteri	Symbol	Rating	Unit		
Drain-source voltage			V _{DSS}	40	V
Gate-source voltage			V _{GSS}	±20]
Drain current (DC)		(Note 1)	Ι _D	120	A
Drain current (pulsed)		(Note 1)	I _{DP}	360	1
Power dissipation	(T _c = 25 °C)		PD	132	w
Power dissipation	(t = 10 s)	(Note 2)		3.0	1
Power dissipation	(t = 10 s)	(Note 3)		0.96	1
Single-pulse avalanche energy		(Note 4)	E _{AS}	140	mJ
Single-pulse avalanche current			I _{AS}	120	A
Channel temperature		(Note 5)	T _{ch}	175	°C
Storage temperature		(Note 5)	T _{stg}	-55 to 175	1

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Channel-to-case thermal impedance	(T _c = 25 °C)		Z _{th(ch-c)}	1.13	°C/W
Channel-to-ambient thermal impedance	(t = 10 s)	(Note 2)	Z _{th(ch-a)}	50	
Channel-to-ambient thermal impedance	(t = 10 s)	(Note 3)	Z _{th(ch-a)}	156	

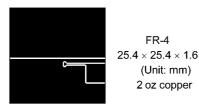
Note 1: Ensure that the channel temperature does not exceed 175 °C.

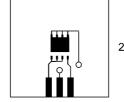
Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V_{DD} = 32 V, T_{ch} = 25 °C (initial), L = 7.47 μ H, R_G = 25 Ω , I_{AS} = 120 A

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.





FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2 oz copper

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	_	_	±1	μA
Drain cut-off current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	_	—	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	40	—	_	V
	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	20	_	_	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.5 mA	2.0	_	3.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 6 V, I _D = 60 A		1.30	1.96	mΩ
		V _{GS} = 10 V, I _D = 60 A		0.95	1.14	

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 300 kHz		4560	_	pF
Reverse transfer capacitance	C _{rss}			320	_	
Output capacitance	C _{oss}]		2940	_	
Gate resistance	rg			2.9	_	Ω
Switching time (rise time)	tr	See Fig. 6.2.1	_	8	_	ns
Switching time (turn-on time)	t _{on}			22	_	
Switching time (fall time)	t _f			23	_	
Switching time (turn-off time)	t _{off}		_	71	_	

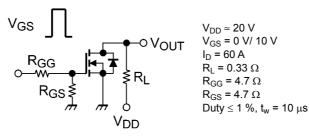


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

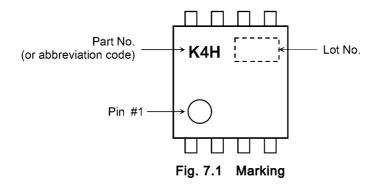
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 32$ V, V_{GS} = 10 V, I_D = 120 A		55	_	nC
Gate-source charge 1	Q _{gs1}		_	20	_	
Gate-drain charge	Q _{gd}		_	13	_	

6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

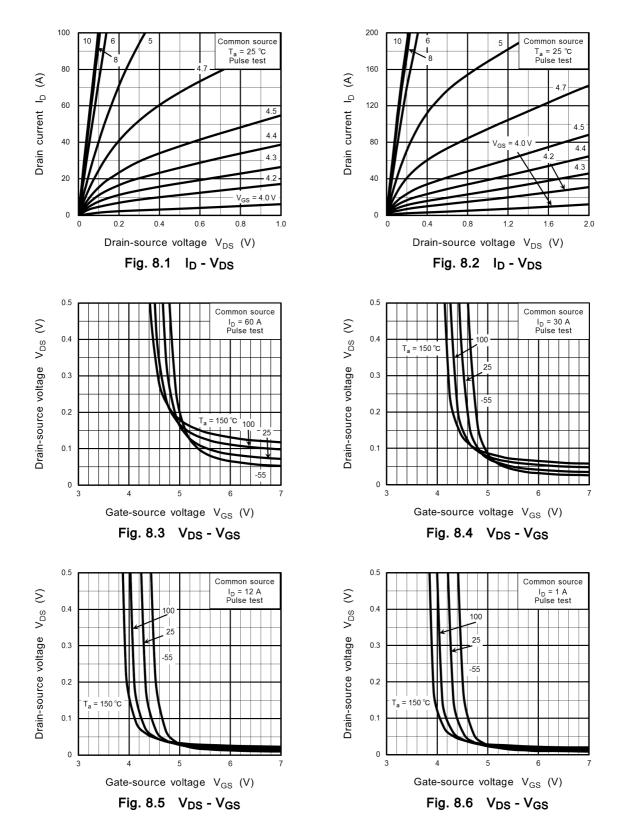
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 6)	I _{DRP}	—	_	—	360	А
Diode forward voltage		V _{DSF}	I _{DR} = 120 A, V _{GS} = 0 V		_	-1.2	V

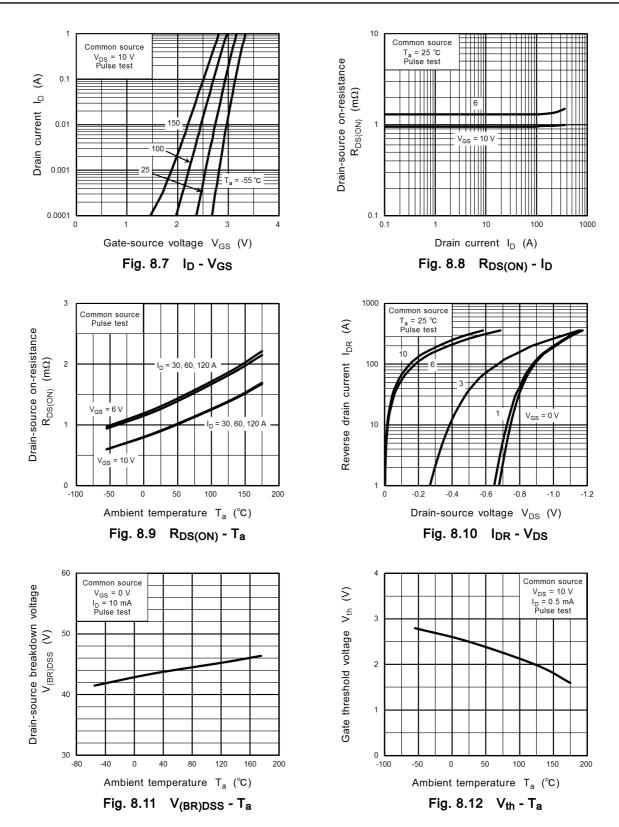
Note 6: Ensure that the channel temperature does not exceed 175 °C.

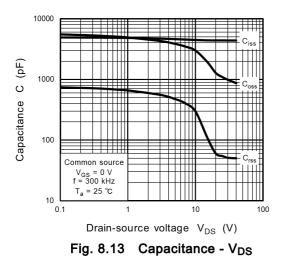
7. Marking



8. Characteristics Curves (Note)







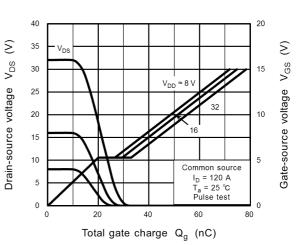


Fig. 8.14 Dynamic Input/Output Characteristics

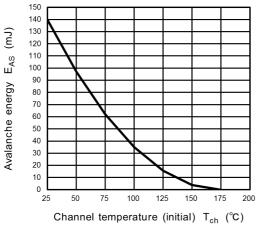


Fig. 8.15 E_{AS} - T_{ch}(Guaranteed Maximum)

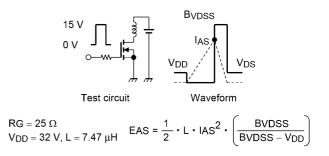
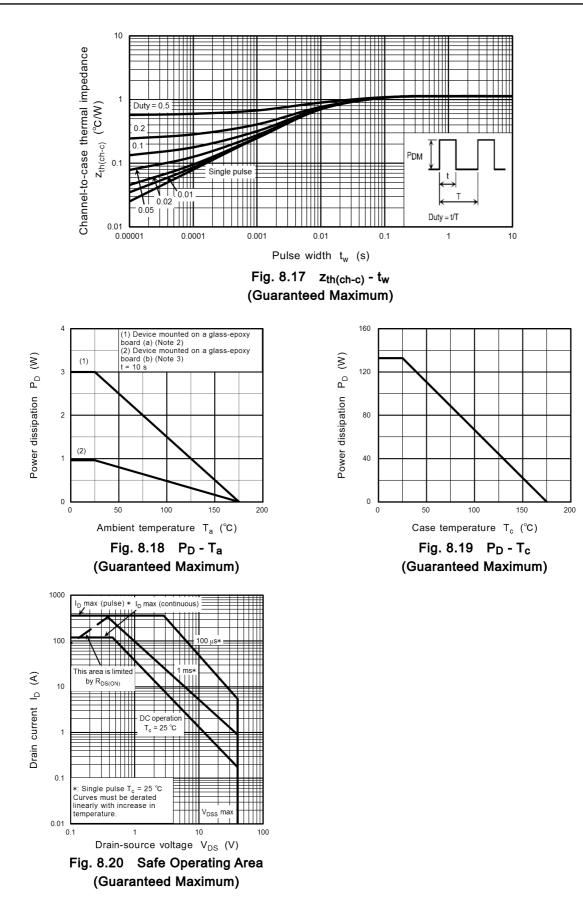


Fig. 8.16 Test Circuit/Waveform

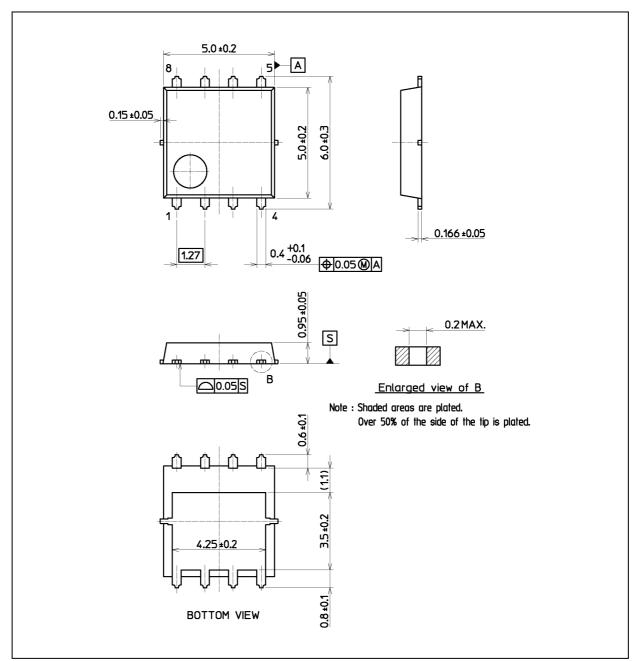


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

XPH1R104PS

Package Dimensions

Unit: mm



Weight: 0.080 g (typ.)

Package Name(s)			
TOSHIBA: 2-5Q4A			
Nickname: SOP Advance(WF)			

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